ABSTRACT OF THE DISCLOSURE

In a production method for manufacturing a plurality of chip-size packages, a plurality of semiconductor chip areas are defined on a surface of a wafer, each of the chip areas being produced as a semiconductor device having a plurality of electrode pads formed thereon. A plurality of sprout-shaped metal bumps formed on each device such that the respective metal bumps are bonded on the pads formed on a corresponding semiconductor device. A resin-sealing layer is formed on the surface of the wafer such that tips of the metal bumps formed on each of the devices are projected from a top surface of the resin-sealing layer. A plurality of wiring patterns are formed on the top surface of the resin-sealing layer such that each of the wiring patterns is allocated to a corresponding semiconductor device, and such that electrical connections are established between each of the wiring patterns and the tips of the metal bumps formed on the corresponding semiconductor device. A plurality of metal balls are formed on each of the wiring patterns such that electrical connections are established therebetween.